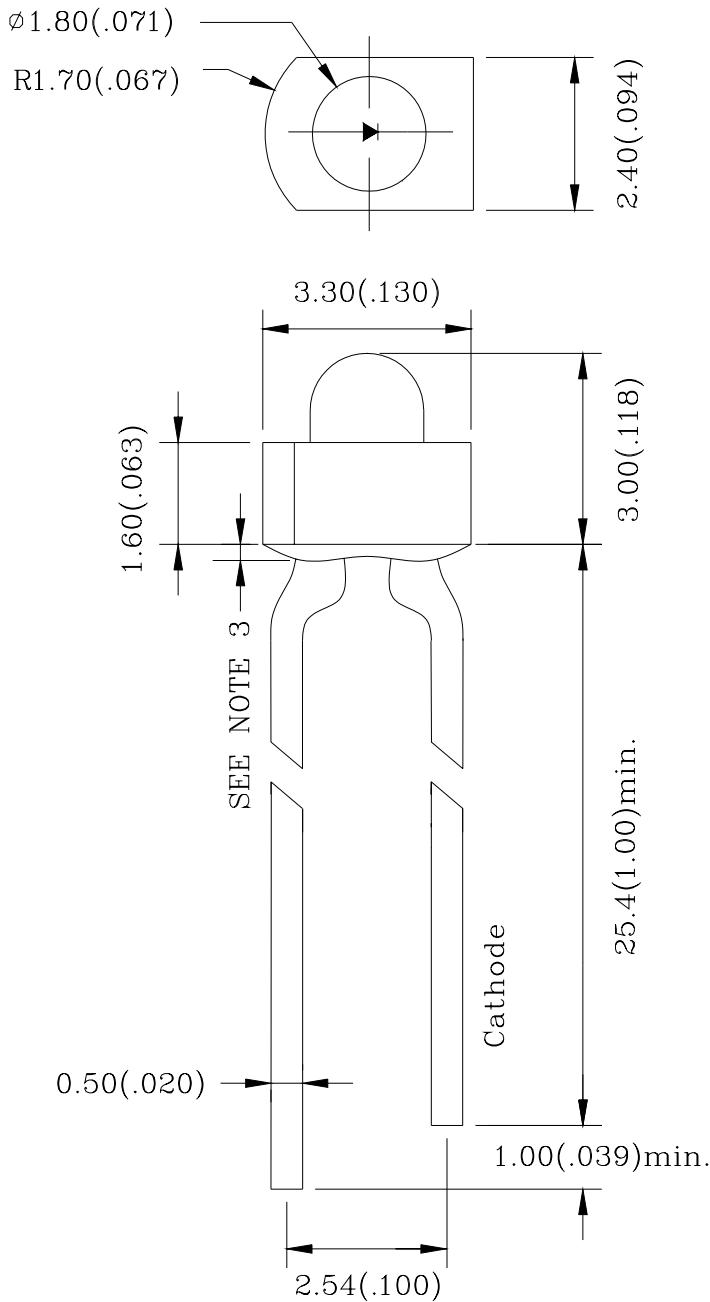


## PACKAGE DIMENSIONS



## Note:

- 1.All Dimensions are in millimeters.
- 2.Tolerance is  $\pm 0.25\text{mm}(0.010\text{ ''})$   
Unless otherwise specified.
- 3.Protruded resin under flange  
is  $1.5\text{mm}(0.059\text{ ''})$  max.
- 4.Lead spacing is measured where  
the leads emerge from the package.
- 5.Specification are subject to change  
without notice.
- 6.highlight  $< -500\text{V}$  the led can  
withstand the max static level when  
assembling or operation.

**FEATURES**

- \* SUITABLE HIGH PULSE CURRENT OPERATION
- \* EXTRA HIGH RADIANT POWER AND RADIANT INTENSITY
- \* HIGH RELIABILITY
- \* LOW FORWARD VOLTAGE

**CHIP MATERIALS**

- \* Dice Material : GaInN/GaN
- \* Light Color : ULTRA ORANGE
- \* Lens Color : ORANGE DIFFUSED

**ABSOLUTE MAXIMUM RATING:(Ta=25°C)**

SYMBOL	DESCRIPTION	ULTRA ORANGE	UNIT
PAD	Power Dissipation Per Chip	80	mW
VR	Reverse Voltage Per Chip	5	V
IF	Average Forward Current Per Chip	20	mA
-	Derating Linear From 25°C Per Chip	0.4	mA/°C
Topr	Operating Temperature Range	-25°C to 85°C	
Tstg	Storage Temperature Range	-40°C to 85°C	
Lead Soldering Temperature { 1.6mm(0.063 inch) From Body } 260°C±5°C For 5 Seconds			

**ELECTRO-OPTICAL CHARACTERISTICS:(Ta=25°C)**

SYMBOL	DESCRIPTION	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VF	Forward Voltage	IF = 20mA		2.2		V
IR	Reverse Current	VR = 5V			100	µA
λD	Dominant Wavelength	IF = 20mA		605		nm
Δλ	Spectral Line Half-Width	IF = 20mA		30		nm
2θ1/2	Half Intensity Angle	IF = 20mA		50		deg
IV	Luminous Intensity	IF = 20mA		550		mcd

